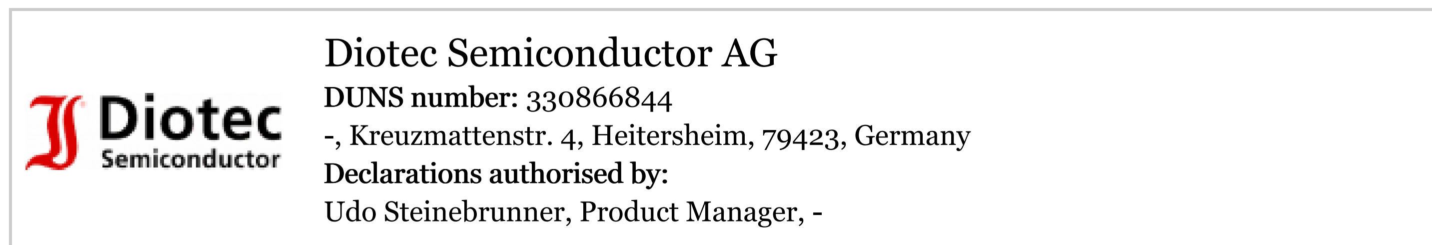
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 26 August 2020, 12:19 GMT



Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2020 [Approved on 26 August 2020, 12:18 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.89%	Silver	7440-22-4	1.5%
			Silicon dioxide	14808-60-7	5.05%
			Silicon	7440-21-3	93.45%
Die attach	Sn-Pb solder	4.37%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	44.78%	Carbon black	1333-86-4	0.5%
			ANTIMONY TRIOXIDE	1309-64-4	0.8%
			Tetrabromobisphenol A	79-94-7	0.99%
			ALUMINUM(III) HYDROXIDE	21645-51-2	2.8%
			resin	9060-05-3	8.6%
			Epoxy resin 89	26335-32-0	16.21%
			Silica, Crystalline	14808-60-7	70.1%
Leadfinish	Tin plating	0.55%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.41%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
PowerSOD-323/DO-219AB	PowerSOD-323/DO-219AB	0.005	g

No need to provide safe use information beyond the identification of the Candidate List substance